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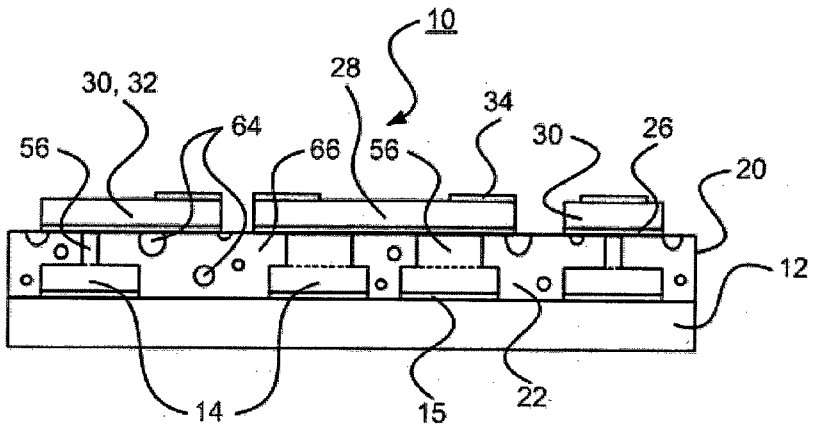


FIG. 21

(57) Abstract: A method of forming a substrate (10) for semiconductor packaging and a substrate (10) for semiconductor packaging are provided. The method includes providing a carrier (12) and forming a plurality of external pads (14) on the carrier (12), the external pads (14) formed on the carrier (12) defining a first conductive layer. A molding operation is performed to form a first insulating layer (20) on the carrier (12) with a molding compound (22). The first conductive layer is embedded in the first insulating layer (20). One or more of a plurality of bond pads (30), a plurality of conductive traces (32) and a plurality of microvias (56) are formed on the first conductive layer, the one or more of the bond pads (30), the conductive traces (32) and the microvias (56) formed on the first conductive layer defining a second conductive layer.

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